Customer Engagement
RJR Polymers value its customers’ goals and schedules. As such, the company operates with an intense focus on making your goals our own. We provide our customers with unsurpassed service and support. We have also designed our solutions to be flexible enough to allow for the division of labor during the packaging process. Many process steps can either be performed by RJR Polymers for the customer, or be brought in-house by the customer. Please contact our customer service team to start the dialogue and find out how RJR Polymers, Inc. can take your semiconductor packaging to new levels.
ITS - Isothermal Sealing Systems

RJR Polymers is a leader in developing Sealing Technologies that seal air cavity packages from environmental contamination in the final stage of package assembly.

We use a patented Isothermal Sealing System (ITS) to achieve:
- A substantial decrease in yield losses due to Blowouts (yielding nearly 100%),
- Increase in throughput because of faster cycle times,
- Increases in location accuracy (machine vs. manual)
- Increase in reliability because of more consistent seals.

Interchangeable custom insert plates enable a single ITS to seal a variety of different package types, including:
- Microwave / RF devices
- Large hybrids
- Oscillator arrays
- CCD / CMOS
- High frequency plastic packages
- BFA / PGA

Major Advantages
- Produces 99%+ yield in seal consistency
- Eliminates blowouts in epoxy seals
- Accuracy location tolerance up to 0.001 inches
- Seals a wide variety of package formats
- Includes microprocessor-based control system
- Allows defective packages to be reworked
- Eliminates excess handling of expensive devices
- Maximizes use of operator’s time

Pre-applied Epoxy and Lids

RJR Polymers has long been a value-added supplier of epoxy coated IC covers and components as well as customer furnished material. RJR has made the process of attaching protective lids to electronic packages faster, more reliable, and less expensive since 1987.

All of RJR materials are custom formulated b-stage epoxies and are applied in-house assuring that the quality and specific performance characteristics are tightly controlled on every batch. RJR materials have consistently out-performed the competition – high moisture vapor resistance, and helium leak free seals are standard performance characteristics.

B-stage Epoxy Features:
- Wide variety of custom materials available
- Cure times down to 5 minutes total
- High moisture vapor resistance
- Low ionics
- Very low volatiles (outgassing)
- Low modulus material for packages with high CTE mismatch

Pre-applied components materials
- Plastic
- Composites
- Glass
- Ceramic
- Metal

Adhesive Options
- Electrically Conductive
- Thermally Conductive

(510) 638-5901
www.rjrpolymers.com

LCP Air Cavity Packages

RJR Polymer is a leading developer of high performance, air cavity LCP packages. The technology allows for injection molded packaging process to combine the thermal advantages of a eutectic die attach with a moisture resistance plastic specifically designed to manage the higher power and frequency previously found only in ceramic packaging systems.

RF Power - LD Products
- Three piece package design
- High thermally conductive bases
- Multi-leaded packages

Microwave and sensors - RQFN Products
- Copper lead frame
- Improved thermal
- Higher frequencies
- Lower inductance
- Design flexibility with lead frame

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